

### **IN THE CLAIMS**

Please amend the claims as follows.

1-35. (Canceled)

36. (Currently Amended) A device comprising:  
a dispenser configured to release a chemical toward an edge bead; and  
a splash controller concentrically positioned at least partially around said dispenser, and  
physically unattached from the edge bead, [[and]] the splash controller being configured to  
draw the chemical toward said splash controller,  
wherein said splash controller is configured to generate a gas pressure around the edge  
bead that is lower than an ambient gas pressure, and wherein said splash controller is  
configured to physically intercept the chemical.

37. (Previously Presented) The device in claim 36, wherein the splash controller is around  
the edge bead.

38. (Previously Presented) The device of claim 36, wherein the splash controller completely  
surrounds said dispenser.

39. (Previously Presented) The device of claim 36, wherein the dispenser has a diameter  
smaller than a diameter of the splash controller.

40. (Previously Presented) The device of claim 36, wherein said dispenser is configured to  
release a chemical on a first side of a wafer and a second side of the wafer toward an edge bead,  
wherein the splash controller completely surrounds said dispenser.

41. (Currently Amended) A device comprising:  
a dispenser configured to release a chemical toward an edge bead on a semiconductor  
substrate; and

a splash controller including a vacuum port, wherein the vacuum port ~~completely surrounds~~ is concentrically positioned about the dispenser, wherein the vacuum port is configured to generate a gas pressure around the edge bead and the dispenser, the generated gas pressure being sufficiently lower than an ambient gas pressure to draw the chemical toward the splash controller, wherein the dispenser has a smaller diameter than the vacuum port, and wherein the splash controller is configured to physically intercept the chemical.